CONTENTS

Technical Reports

Overview .................................................................1
by Yukio Yasuda

Development of SiC-MOSFET Chip Technology .............2
by Masayuki Imaizumi

Development of Wiring Technologies to Improve Power Module Performance ........................................5
by Yoshihisa Uchida and Arata Iizuka

2000 V Class IGBT Concept for Renewable Energy Converter ..9
by Satoshi Miyahara and Masaomi Miyazawa

Humidity Robustness Verification Test for HVIGBT Modules ..13
by Kenji Hatori and Keiichi Nakamura

Development of Surface-mount IPM ................................17
by Shuhei Yokoyama and Shogo Shibata

Precis

Mitsubishi Electric’s power modules, which employ the latest chip and package technology, realize ideal power electronics systems thanks to their high quality, low loss, and excellent noise performance.